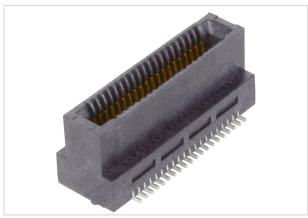
har-flex HD-CE 40 w/o hold PL1 Sample



| Part number | 15 03 040 2001 333 |
|--------------------|--|
| Specification | har-flex HD-CE 40 w/o hold PL1 Sample |
| HARTING eCatalogue | https://b2b.harting.com/15030402001333 |

Image is for illustration purposes only. Please refer to product description.

Identification

| Category | Connectors |
|----------------|-----------------------|
| Series | har-flex [®] |
| Identification | HD-Card Edge |
| Element | Connector |

Version

| Termination method | Reflow soldering termination (SMT) |
|--------------------|---------------------------------------|
| Connection type | Motherboard to daughtercard Mezzanine |
| Number of contacts | 40 |
| Performance level | 1 |
| Pack contents | Sample |

Technical characteristics

| Contact rows | 2 |
|------------------------------------|---|
| Contact spacing (termination side) | 0.8 mm |
| Clearance distance | ≥0.2 mm Backplane ≥0.53 mm Connector ≥0.1 mm Daughtercard |
| Creepage distance | ≥0.2 mm Backplane ≥0.53 mm Connector ≥0.1 mm Daughtercard |
| Limiting temperature | -55 +125 °C |
| Insertion force | ≤25 N |
| Withdrawal force | ≥8 N |



Technical characteristics

| Mating cycles | ≥200 |
|----------------------------------|-------------------------------------|
| Data rate | 25 Gbit/s |
| Isolation group | Illa (175 ≤ CTI < 400) |
| Moisture Sensitivity Level (MSL) | 1 acc. to ECA/IPC/JEDEC J-STD-020D |
| Process Sensitivity Level (PSL) | R0 acc. to ECA/IPC/JEDEC J-STD-020D |
| Coplanarity of contacts | ≤0.1 mm |

Material properties

| Material (insert) | Liquid crystal polymer (LCP) |
|---|---|
| Colour (insert) | Black |
| Material (contacts) | Copper alloy |
| Surface (contacts) | Au over Pd/Ni Mating side Tin plated Termination side |
| Material flammability class acc. to UL 94 | V-0 |

Commercial data

| Packaging size | 1 |
|-------------------|--|
| Country of origin | China |
| eCl@ss | 27460201 PCB connector (board connector) |